

3.2x1.0 x1.5mm Side View RGB Chip LED

OSTB1204C1E

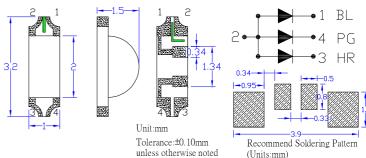
■Features

- Bi-Color
- Super high brightness of side view LED
- Compact package outline (L x W x T) of 3.2mm x 1.0mm x 1.5mm
- Compatible to IR reflow soldering.
- White Diffused Type.

Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Outline Dimension

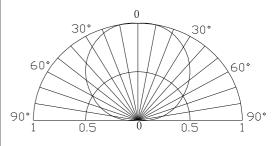


(Units:mm)

■Absolute Maximum Rating

Item	Cromb of	Value				
Item	Symbol	R	B/G	Unit		
DC Forward Current	I_F	30	30	mA		
Pulse Forward Current*	I_{FP}	100	100	mA		
Reverse Voltage	V_R	5	5	V		
Power Dissipation	P_D	78	108	mW		
Operating Temperature	Topr	-40 ~	$^{\circ}$ C			
Storage Temperature	Tstg	-40~ +85				
Lead Soldering Temperature	Tsol	260°C	-			

Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

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	Color		$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)			2θ1/2(deg)			
Part Number			Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	
			I _F =20mA		V _R =5V	I _F =20mA								
OSTB1204C1E	Red	R		1.8	2.1	2.6	10	100	200	-	618	620	625	120
	Pure Green	G		2.8	3.1	3.6	10	350	500	-	515	518	524	120
	Blue	В		2.8	3.1	3.6	10	100	200	-	462	466	472	120

^{*1} Tolerance of measurements of dominant wavelength is ±1nm

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^{*}Pulse width Max 0.1ms, Duty ratio max 1/10

^{*2} Tolerance of measurements of luminous intensity is ±15%

^{*3} Tolerance of measurements of forward voltage is ± 0.1 V



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■ Cautions:

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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